Supplementary information for

## Anisotropic ionic transport-controlled synaptic weight update by protonation

## in VO<sub>2</sub> transistor

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Figure S1 | Epitaxial growth of (101)<sub>R</sub> and (100)<sub>R</sub> VO<sub>2</sub> thin films. a. Structural analysis of epitaxial (101)<sub>R</sub> and (100)<sub>R</sub> VO<sub>2</sub> films on (101) and (100) TiO<sub>2</sub> substrates. b. The rocking curves of both VO<sub>2</sub> diffraction peaks were shown, and they show similar FWHM value as 0.025°. c. Sheet resistance (R<sub>S</sub>) – Temperature (K) measurements from 300 K to 395 K during heating and cooling process of both VO<sub>2</sub> films. They show similar R<sub>S</sub> change during their intrinsic metal-insulator transition (MIT) phenomena.





**Figure S2** | **Device fabrication process. a.** Epitaxial 10-nm-thick  $(101)_R$  and  $(100)_R$  VO<sub>2</sub> thin films were prepared by PLD methods. **b.** VO<sub>2</sub> channel were defined by photolithography followed by wet HNO<sub>3</sub> etching process. **c.** 30-nm-thick Pt source and drain electrodes were deposited by RF sputtering. **d.** 300-nm-thick porous silica layer were spin-coated followed by curing process. **e.** 30-nm-thick Pt gate electrode were deposited by RF sputtering. **f.** The porous silica layer on the area of source and drain electrode were wet etched with oxide etchant for contact.





Figure S3 | Specific capacitance as a function of frequencies. The frequency-dependent capacitance measurements (*C-f*, 1 kHz  $\leq f \leq 5$  MHz) were performed on the Pt (gate)/electrolyte/VO<sub>2</sub> stack. the specific capacitance decreased with  $f (\sim 0.4 \,\mu\text{F/cm}^2 \text{ at } 1 \,\text{kHz} \rightarrow \sim 0.02 \,\mu\text{F/cm}^2 \text{ at } 5 \,\text{MHz})$  due to the slow response of mobile protons in porous silica with respect to high- $f V_G$ .





Figure S4 | Excitatory postsynaptic current (EPSC) triggered by  $D_P$  (= 20, 30, and 50 ms) of  $V_{pre}$  pulse as a function of  $A_P$  of  $V_{pre}$  in (101)<sub>R</sub> and (100)<sub>R</sub>-VO<sub>2</sub> synaptic transistors.





Figure S5 | EPSC peak of single V<sub>pre</sub> pulse as a function of  $D_P$  and  $A_P$  (101)<sub>R</sub> and (100)<sub>R</sub>-VO<sub>2</sub> synaptic transistors. The similar value of EPSC with short  $D_P$  (= 10 ms) and long  $D_P$  (=100 ms) at small  $A_P$  (= 0.5 V) means that there is no additional H<sup>+</sup> incorporation with long  $D_P$ . However, the EPSC with short  $D_P$  (= 10 ms) and long  $D_P$  (=100 ms) at large  $A_P$  (= 3.0 V) shows significant differences due to the large amount of H<sup>+</sup> incorporation in VO<sub>2</sub> lattices.





Figure S6 | The memory retention in the both VO<sub>2</sub> synaptic transistors with  $A_P$  (= 0.5 - 3.0 V) and  $D_P$  (= 30, 50, and 100 ms). The power function  $\gamma = b \times t^{-m}$ , where  $\gamma$  is the memory retention, b is the initial value, t is time, and m is the decay rate. Retention time increases as m decreases. By quantitative evaluation, in the same transistor, m decreased with increase in  $A_P$ and  $D_P$ .





**Figure S7** | **a.** a short  $D_P$  of  $V_{pre}$  pulse (= 10 ms) and **b.** a long  $D_P$  of  $V_{pre}$  pulse (= 100 ms) as a function of the  $A_P$  of  $V_{pre}$  in (101)<sub>R</sub> and (100)<sub>R</sub>-VO<sub>2</sub> synaptic transistors in logarithmic scale.

## Figure S8



Figure S8 | Potentiation and Depression of  $(101)_R$  and  $(100)_R$  VO<sub>2</sub> synaptic transistors





Figure S9 | the crystallographic axes of monoclinic  $VO_2$  and rutile  $VO_2$  phases